

DUAL MONOSTABLE MULTIVIBRATOR

- HIGH SPEED : t_{PD} = 24 ns (TYP.) at V_{CC} = 6V
- LOW POWER DISSIPATION: STAND BY STATE : $I_{CC}=4\mu A$ (MAX.) at $T_A=25^{\circ}C$ ACTIVE STATE : $I_{CC}=700\mu A$ (TYP.) at $V_{CC}=6V$
- HIGH NOISE IMMUNITY:
 V_{NIH} = V_{NIL} = 28 % V_{CC} (MIN.)
- SYMMETRICAL OUTPUT IMPEDANCE: |I_{OH}| = I_{OL} = 4mA (MIN)
- BALANCED PROPAGATION DELAYS: t_{PLH} ≅ t_{PHL}
- WIDE OPERATING VOLTAGE RANGE: V_{CC} (OPR) = 2V to 6V
- WIDE OUTPUT PULSE WIDTH RANGE : t_{WOUT} = 150 ns ~ 60 s OVER AT V_{CC} = 4.5 V
- PIN AND FUNCTION COMPATIBLE WITH 74 SERIES 221

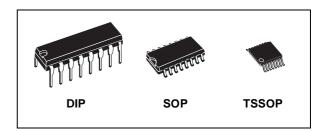
DESCRIPTION

The M74HC221A is an high speed CMOS MONOSTABLE MULTIVIBRATOR fabricated with silicon gate C²MOS technology.

There are two trigger inputs, A INPUT (negative edge) and B INPUT (positive edge).

Triggering on the B input occurs at a particular voltage threshold and is not related to rise and fall time of the applied pulse. The device may also be trigger by using the CLR input (positive edge) because of the Schimtt-trigger input; after

PIN CONNECTION AND IEC LOGIC SYMBOLS



ORDER CODES

PACKAGE	TUBE	T & R
DIP	M74HC221AB1R	
SOP	M74HC221AM1R	M74HC221ARM13TR
TSSOP		M74HC221ATTR

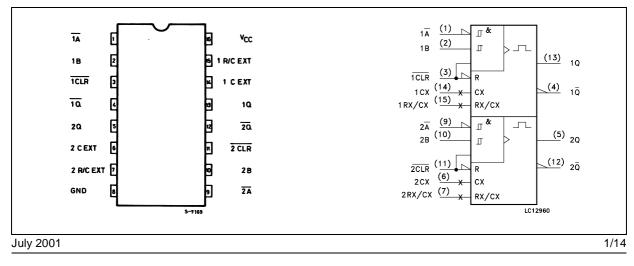
triggering the output maintains the MONOSTABLE STATE for the time period determined by the external resistor Rx and capacitor Cx. Taking CLR low breaks this MONOSTABLE STATE. If the next trigger pulse occurs during the MONOSTABLE period it makes the MONOSTABLE period longer. Limit for values of Cx and Rx :

Cx : NO LIMIT

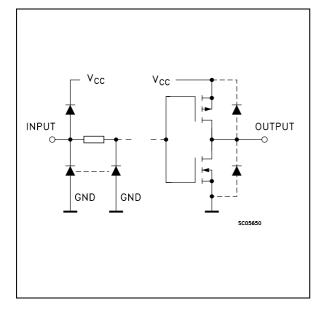
 $\text{Rx}:\text{V}_{\text{cc}}~<~3.0\text{V}~5\text{K}\Omega$ to $1\text{M}\Omega$

 $\tilde{V_{cc}} \ge 3.0V \ 1K\Omega$ to $1M\Omega$

All inputs are equipped with protection circuits against static discharge and transient excess voltage.



INPUT AND OUTPUT EQUIVALENT CIRCUIT



PIN DESCRIPTION

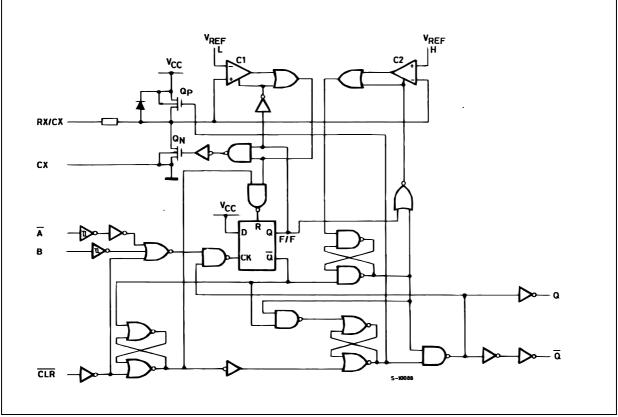
PIN No	SYMBOL	NAME AND FUNCTION
1,9	1 A , 2 A	Trigger Inputs (Negative Edge Triggered)
2, 10	1B, 2B	Trigger Inputs (Positive Edge Triggered)
3, 11	1 <u>CLR</u> 2 CLR	Direct Reset LOW and trigger Action at Positive Edge
4, 12	1Q, 2Q	Outputs (Active Low)
7	2R _X /C _X	External Resistor Capacitor Connection
13, 5	1Q, 2Q	Outputs (Active High)
14, 6	1C _X 2C _X	External Capacitor Connection
15	1R _X /C _X	External Resistor Capacitor Connection
8	GND	Ground (0V)
16	Vcc	Positive Supply Voltage

TRUTH TABLE

	INPUTS		Ουτι	PUTS	NOTE	
Ā	В	CLR	Q	Q	NOTE	
	Н	Н			OUTPUT ENABLE	
Х	L	Н	L(*)	H(*)	INHIBIT	
Н	Х	Н	L(*)	H(*)	INHIBIT	
L		Н			OUTPUT ENABLE	
L	Н				OUTPUT ENABLE	
Х	Х	L	L	Н	INHIBIT	

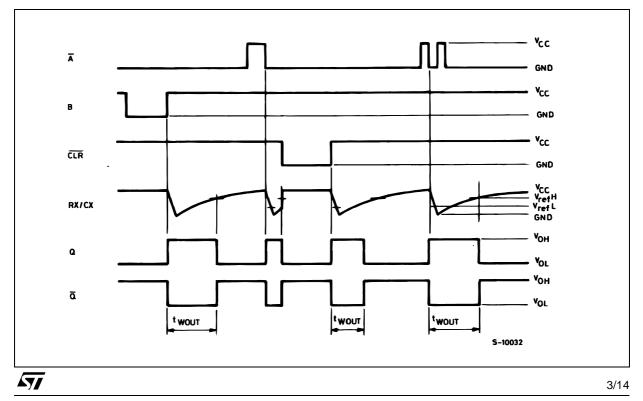
X : Don't Care (*) : Except for monostable period

SYSTEM DIAGRAM

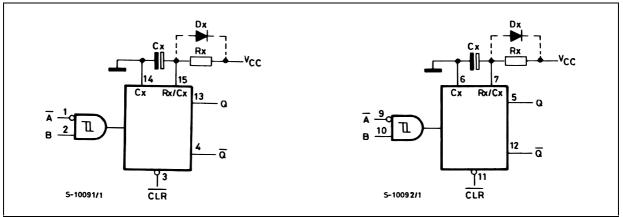


This logic diagram has not be used to estimate propagation delays

TIMING CHART



BLOCK DIAGRAM



(1) Cx, Rx, Dx are external components.(2) Dx is a clamping diode.

The external capacitor is charged to Vcc in the stand-by-state, i.e. no trigger. When the supply voltage is turned off Cx is discharged mainly trough an internal parasitic diode(see figures). If Cx is sufficiently large and Vcc decreases rapidly, there will be some possibility of damaging the I.C. with a surge current or latch-up. If the voltage supply filter capacitor is large enough and Vcc decrease slowly, the surge current is automatically limited and damage to the I.C. is avoided. The maximum forward current of the parasitic diode is approximately 20 mA. In cases where Cx is large the time taken for the supply voltage to fall to 0.4 Vcc can be calculated as follows : $t_f \ge (Vcc - 0.7) \times Cx/20mA$

In cases where t_f is too short an external clamping diode is required to protect the I.C. from the surge current.

FUNCTIONAL DESCRIPTION

STAND-BY STATE

The external capacitor,Cx, is fully charged to Vcc in the stand-by state. Hence, before triggering, transistor Qp and Qn (connected to the Rx/Cx node) are both turned-off. The two comparators that control the timing and the two reference voltage sources stop operating. The total supply current is therefore only leakage current.

TRIGGER OPERATION

Triggering occurs when :

1 st) A is "LOW" and B has a falling edge;

2 nd) B is "HIGH" and A has a rising edge;

3 rd) A is "LOW" and B is HIGH and C1 has a rising edge;

After the multivibrator has been retriggered comparator C1 and C2 start operating and Qn is turned on. Cx then discharges through Qn. The voltage at the node R/C external falls.

When it reaches V_{REFL} the output of comparator C1 becomes low. This in turn reset the flip-flop and Qn is turned off.

At this point C1 stops functioning but C2 continues to operate.

The voltage at R/C external begins to rise with a time constant set by the external components Rx, Cx.

Triggering the multivibrator causes Q to go high after internal delay due to the flip-flop and the gate. Q remains high until the voltage at R/C external rises again to V_{REFH} . At this point C2 output goes low and O goes low. C2 stop operating. That means that after triggering when the voltage R/C external returns to V_{REFH} the multivibrator has returned to its MONOSTABLE STATE. In the case where Rx \cdot Cx are large enough and the discharge time of the capacitor and the delay time in the I.C. can be ignored, the width of the output pulse tw (out) is as follows :

$$tW(OUT) = Cx \cdot Rx$$

RESET OPERATION

CL is normally high. If CL is low, the trigger is not effective because Q output goes low and trigger control flip-flop is reset.

Also transistor Op is turned on and Cx is charged quickly to Vcc. This means if CL input goes low the IC becomes waiting state both in operating and non operating state.

<u>\</u>

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _{CC}	Supply Voltage	-0.5 to +7	V
VI	DC Input Voltage	-0.5 to V _{CC} + 0.5	V
Vo	DC Output Voltage	-0.5 to V _{CC} + 0.5	V
Ι _{ΙΚ}	DC Input Diode Current	± 20	mA
Ι _{ΟΚ}	DC Output Diode Current	± 20	mA
Ι _Ο	DC Output Current	± 25	mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current	± 50	mA
PD	Power Dissipation	500(*)	mW
T _{stg}	Storage Temperature	-65 to +150	°C
ΤL	Lead Temperature (10 sec)	300	°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied (*) 500mW at 65 °C; derate to 300mW by 10mW/°C from 65°C to 85°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Value	Unit
V _{CC}	Supply Voltage		2 to 6	V
VI	Input Voltage		0 to V _{CC}	V
Vo	Output Voltage		0 to V _{CC}	V
T _{op}	Operating Temperature		-55 to 125	°C
	Input Rise and Fall Time ($\overline{\text{CLR}}$ and $\overline{\text{A}}$ only)	$V_{CC} = 2.0V$	0 to 1000	ns
t _r , t _f		$V_{CC} = 4.5V$	0 to 500	ns
		$V_{CC} = 6.0V$	0 to 400	ns
Сх	External Capacitor		> 100	pF
Rx	External Resistor	Vcc < 3V	5K to 1M	Ω
118		Vcc <u>></u> 3V	1K to 1M	52

The Maximum allowable values of Cx and Rx are a function of leakage of capacitor Cx, the leakage of device and leakage due to the board layout and surface resistance. Susceptibility to externally induced noise may occur for $Rx > 1M\Omega$

DC SPECIFICATIONS

		٦	Test Condition				Value				Unit
Symbol	Parameter	v _{cc}		т	A = 25°	C	-40 to	85°C	-55 to	125°C	
		(V)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
V _{IH}	High Level Input	2.0		1.5			1.5		1.5		
	Voltage	4.5		3.15			3.15		3.15		V
		6.0		4.2			4.2		4.2		
V _{IL}	Low Level Input	2.0				0.5		0.5		0.5	
	Voltage	4.5				1.35		1.35		1.35	V
		6.0				1.8		1.8		1.8	
V _{OH}	High Level Output	2.0	I _O =-20 μΑ	1.9	2.0		1.9		1.9		
	Volt <u>a</u> ge (Q, Q Output)	4.5	I _O =-20 μA	4.4	4.5		4.4		4.4		
	(a, a capat)	6.0	I _O =-20 μA	5.9	6.0		5.9		5.9		V
		4.5	I _O =-4.0 mA	4.18	4.31		4.13		4.10		
		6.0	I _O =-5.2 mA	5.68	5.8		5.63		5.60		
V _{OL}	Low Level Output	2.0	I _O =20 μA		0.0	0.1		0.1		0.1	
	Volt <u>ag</u> e (Q, Q Output)	4.5	I _O =20 μA		0.0	0.1		0.1		0.1	
	(Q, Q Output)	6.0	I _O =20 μA		0.0	0.1		0.1		0.1	V
		4.5	l _O =4.0 mA		0.17	0.26		0.33		0.40	
		6.0	I _O =5.2 mA		0.18	0.26		0.33		0.40	
I _I	Input Leakage Current	6.0	$V_{I} = V_{CC} \text{ or } GND$			± 0.1		± 1		± 1	μΑ
I _I	R/C Terminal Off State Current	6.0	$V_{I} = V_{CC} \text{ or } GND$			± 0.1		± 1		± 1	μΑ
Icc	Quiescent Supply Current	6.0	$V_{I} = V_{CC}$ or GND			4		40		80	μΑ
I _{CC'}	Active State	2.0	$V_{I} = V_{CC} \text{ or } GND$		45	200		260		320	μΑ
	Supply Current (1)	4.5	Pin 7 or 15		500	600		780		960	μΑ
		6.0	$V_{IN} = V_{CC}/2$		0.7	1		1.3		1.6	mA

(1) : Per Circuit

		Т	est Condition				Value				
Symbol	Parameter	v _{cc}		Т	A = 25°	C	-40 to	85°C	-55 to	125°C	Unit
		(V)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
t _{TLH} t _{THL}	Output Transition	2.0			30	75		95		110	
	Time	4.5			8	15		19		22	ns
		6.0			7	13		16		19	
t _{PLH} t _{PHL}	Propagation Delay	2.0			102	210		265		315	
		4.5			30	42		53		63	ns
	(Ā, B - Q, <u>Q</u>)	6.0			24	36		45		54	
t _{PLH} t _{PHL}	Propagation Delay	2.0			102	235		295		355	
	Time(CLR	4.5			30	47		59		71	ns
	TRIGGER - Q, \overline{Q})	6.0			24	40		50		60	
t _{PLH} t _{PHL}	Propagation Delay	2.0			67	160		200		240	
	T <u>ime</u> (CLR - Q, <u>Q</u>)	4.5			20	32		40		48	ns
	(CLR - Q, Q)	6.0			16	27		34		41	
t _{WOUT}	Output Pulse Width	2.0	Cv 100 pF		1.8						
		4.5	Cx = 100 pF Rx = 10KΩ		1.5						μs
		6.0	101(32		1.4						
		2.0	$Cx = 0.1 \mu F$		10						
		4.5	$Rx = 100K\Omega$		9.7						ms
		6.0			9.6						
Δt_{WOUT}	Output Pulse Width Error Between Circuits in Same Package				±1						%
t _{W(H)}	Minimum Pulse	2.0				75		95		110	
t _{W(L)}	Width	4.5				15		19		22	ns
		6.0				13		16		20	
t _{W(L)}	Minimum Pulse	2.0				75		95		110	
	Width	4.5				15		19		22	ns
		6.0				13		16		20	

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6ns$)

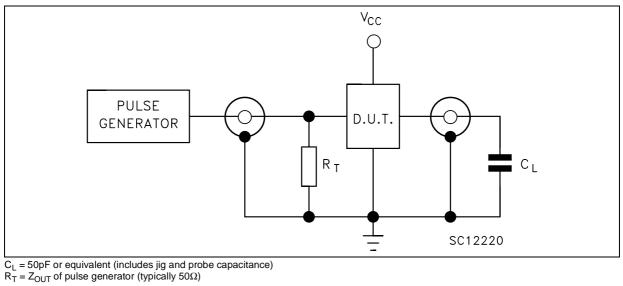
CAPACITIVE CHARACTERISTICS

		٦	Test Condition				Value				
Symbol	Parameter	v _{cc}		Т	_A = 25°	С	-40 to	85°C	-55 to	125°C	Unit
		(V)		Min.	Тур.	Max.	Min.	Max.	Min.	Max.	
C _{IN}	Input Capacitance	5.0			5	10		10		10	pF
C _{PD}	Power Dissipation Capacitance (note 1)	5.0			174						pF

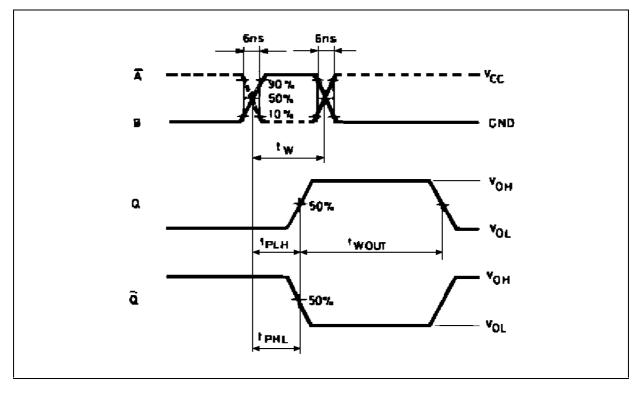
1) C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation. $I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}$ ' Duty/100 + Ic/2(per monostable) (I_{cc} ': Active Supply current) (Duty : %)

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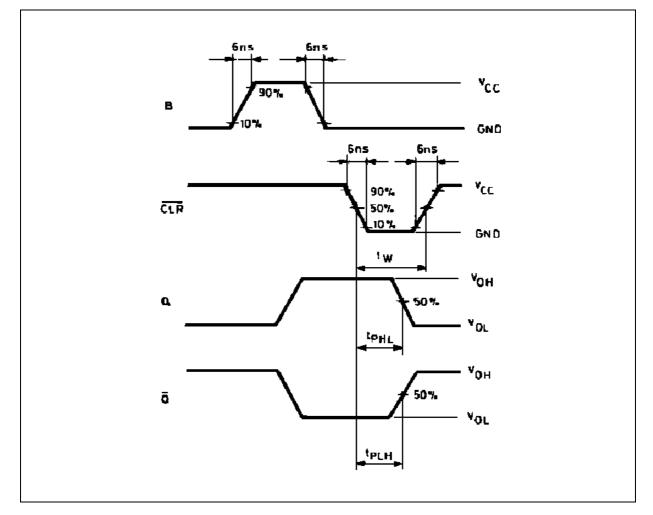
TEST CIRCUIT



WAVEFORM 1: PROPAGATION DELAY TIME, MINIMUM PULSE WIDTH (A, B), OUTPUT PULSE WIDTH (f=1MHz; 50% duty cycle)

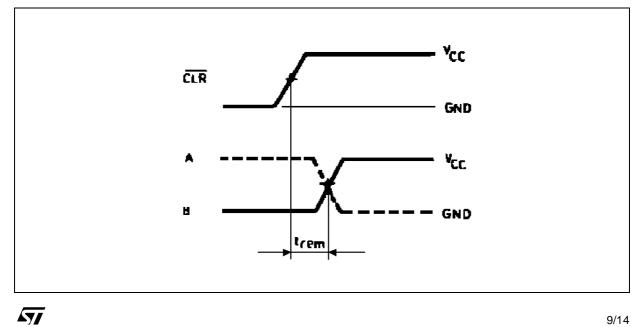


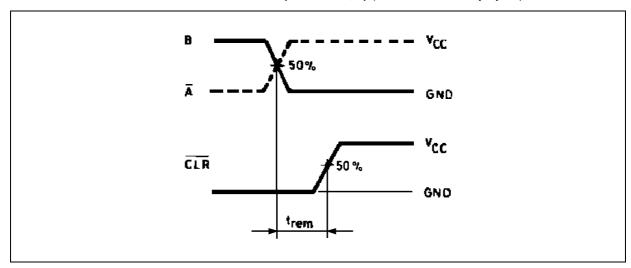
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WAVEFORM 2 : MINIMUM PULSE WIDTH (CLR), PROPAGATION DELAY (f=1MHz; 50% duty cycle)

WAVEFORM 3 : MINIMUM REMOVAL TIME (CLR TO A,B) (f=1MHz; 50% duty cycle)

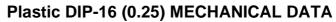


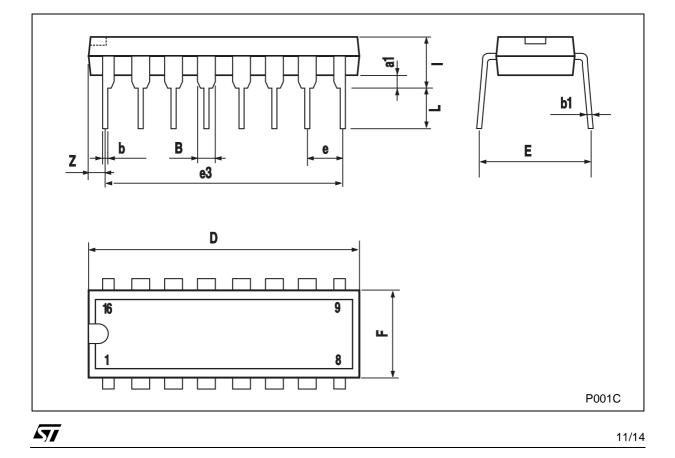


WAVEFORM 4 : MINIMUM REMOVAL TIME (CLR TO A,B) (f=1MHz; 50% duty cycle)

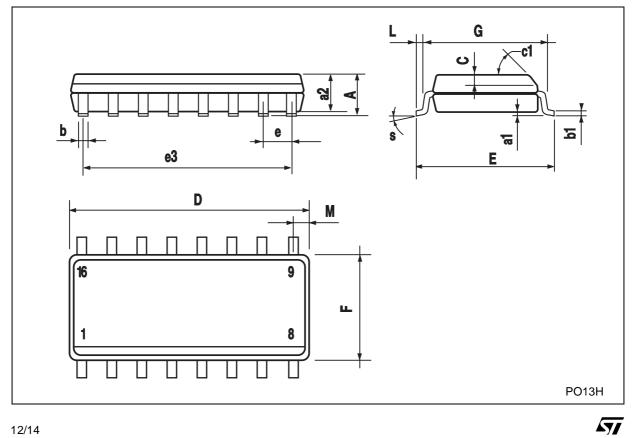


DIM.		mm.			inch					
	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.				
a1	0.51			0.020						
В	0.77		1.65	0.030		0.065				
b		0.5			0.020					
b1		0.25			0.010					
D			20			0.787				
Е		8.5			0.335					
е		2.54			0.100					
e3		17.78			0.700					
F			7.1			0.280				
Ι			5.1			0.201				
L		3.3			0.130					



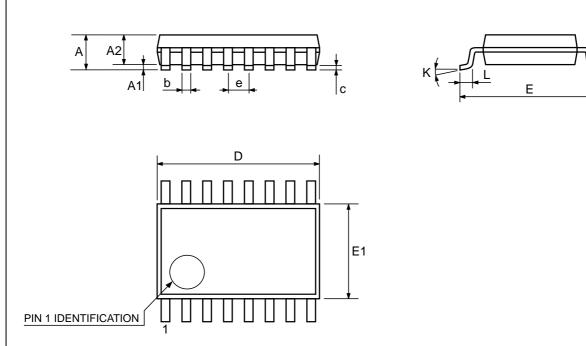


mm. TYP	MAX. 1.75 0.2 1.65 0.46 0.25	MIN. 0.003 0.013 0.007	inch TYP.	MAX. 0.068 0.007 0.064 0.018
	1.75 0.2 1.65 0.46	0.003	TYP.	0.068 0.007 0.064 0.018
0.5	0.2 1.65 0.46	0.013		0.007 0.064 0.018
0.5	1.65 0.46	0.013		0.064
0.5	0.46			0.018
0.5				
0.5	0.25	0.007		0.040
0.5				0.010
0.0			0.019	
	45°	(typ.)		•
	10	0.385		0.393
	6.2	0.228		0.244
1.27			0.050	
8.89			0.350	
	4.0	0.149		0.157
	5.3	0.181		0.208
	1.27	0.019		0.050
	0.62			0.024
		6.2 1.27 8.89 4.0 5.3 1.27 0.62	6.2 0.228 1.27	6.2 0.228 1.27 0.050 8.89 0.350 4.0 0.149 5.3 0.181 1.27 0.019 0.62 0.019



DIM.		mm.				
	MIN.	ТҮР	MAX.	MIN.	TYP.	MAX.
А			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
С	0.09		0.20	0.004		0.0089
D	4.9	5	5.1	0.193	0.197	0.201
Е	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
е		0.65 BSC			0.0256 BSC	
К	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030





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